OptiMOS®-T Power-Transistor

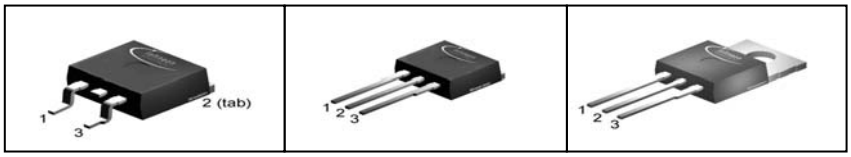
Features

- N-channel - Enhancement mode
- Automotive AEC Q101 qualified
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- Green package (lead free)
- Ultra low Rds(on)
- 100% Avalanche tested

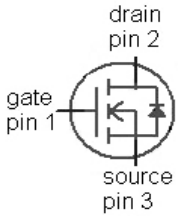
Product Summary

V_{DS}	55	V
$R_{DS(on),max}$ (SMD version)	4.1	mΩ
I_D	100	A

PG-TO263-3-2 | PG-TO262-3-1 | PG-TO220-3-1



Type	Package	Ordering Code	Marking
IPB100N06S3-04	PG-TO263-3-2	SP0001-02220	3PN0604
IPI100N06S3-04	PG-TO262-3-1	SP0001-02210	3PN0604
IPP100N06S3-04	PG-TO220-3-1	SP0001-02212	3PN0604



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current[1]	I_D	T_C=25 °C, V_{GS}=10 V	100	A
		T_C=100 °C, V_{GS}=10 V[2]	100	
Pulsed drain current[2]	$I_{D,pulse}$	T_C=25 °C	400	
Avalanche energy, single pulse[3]	E_{AS}	I_D=50 A	450	mJ
Drain gate voltage[2]	V_{DG}		55	V
Gate source voltage[4]	V_{GS}		±20	V
Power dissipation	P_{tot}	T_C=25 °C	214	W
Operating and storage temperature	T_j, T_{stg}		-55 ... +175	°C
IEC climatic category; DIN IEC 68-1			55/175/56	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics[2]						
Thermal resistance, junction - case	R_{thJC}		-	-	0.7	K/W
Thermal resistance, junction - ambient, leaded	R_{thJA}		-	-	62	
SMD version, device on PCB	R_{thJA}	minimal footprint	-	-	62	
		6 cm^2 cooling area[5]	-	-	40	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D= 1 mA	55	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=150 µA	2.1	3.0	4.0	
Zero gate voltage drain current	I_{DSS}	V_{DS}=55 V, V_{GS}=0 V, T_j=25 °C	-	0.01	1	µA
		V_{DS}=55 V, V_{GS}=0 V, T_j=125 °C[2]	-	1	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	1	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=10 V, I_D=80 A	-	3.5	4.4	mΩ
		V_{GS}=10 V, I_D=80 A, SMD version	-	3.2	4.1	

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics[2]						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=25 V, f=1 MHz	-	14230	-	pF
Output capacitance	C_{oss}		-	2165	-	
Reverse transfer capacitance	C_{rss}		-	2070	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=27.5 V, V_{GS}=10 V, I_D=80 A, R_G=3.3 Ω	-	46	-	ns
Rise time	t_r		-	62	-	
Turn-off delay time	$t_{d(off)}$		-	62	-	
Fall time	t_f		-	62	-	
Gate Charge Characteristics[2]						
Gate to source charge	Q_{gs}	V_{DD}=11 V, I_D=80 A, V_{GS}=0 to 10 V	-	91	-	nC
Gate to drain charge	Q_{gd}		-	47	-	
Gate charge total	Q_g		-	209	314	
Gate plateau voltage	$V_{plateau}$		-	5.8	-	V
Reverse Diode						
Diode continous forward current[2]	I_S	T_C=25 °C	-	-	100	A
Diode pulse current[2]	$I_{S,pulse}$		-	-	400	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=80 A, T_j=25 °C	0.6	0.9	1.3	V
Reverse recovery time[2]	t_{rr}	V_R=27.5 V, I_F=I_S, di_F/dt=100 A/µs	-	-		ns
Reverse recovery charge[2]	Q_{rr}		-	-	-	nC

[1] Current is limited by bondwire; with an R_{thJC} = 0.7 K/W the chip is able to carry 164 A at 25°C. For detailed information see Application Note ANPS071E at *www.infineon.com/optimos*

[2] Defined by design. Not subject to production test.

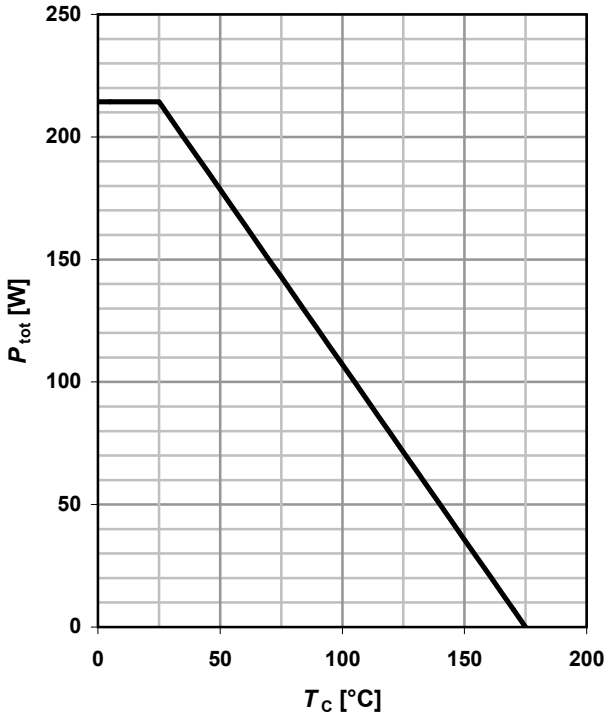
[3] See diagrams 12 and 13.

[4] Qualified at -5V and +20V.

[5] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm^2 (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

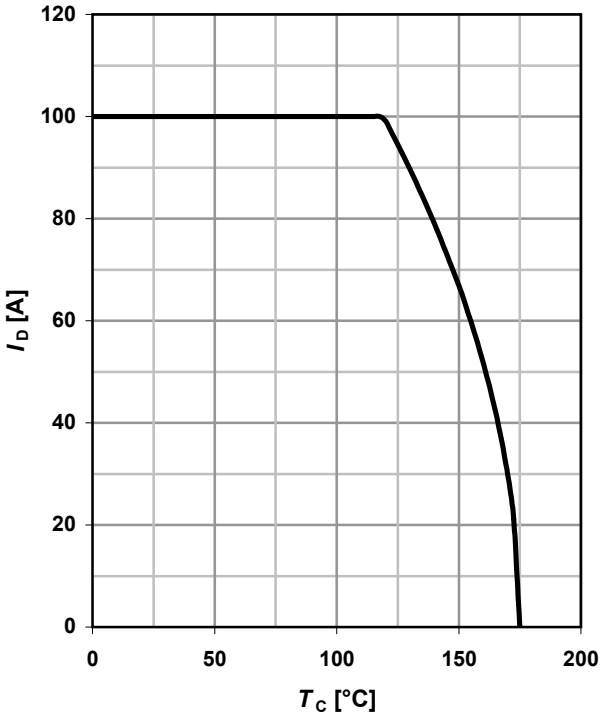
1 Power dissipation

$P_{tot} = f(T_C)$; $V_{GS} \geq 6$ V



2 Drain current

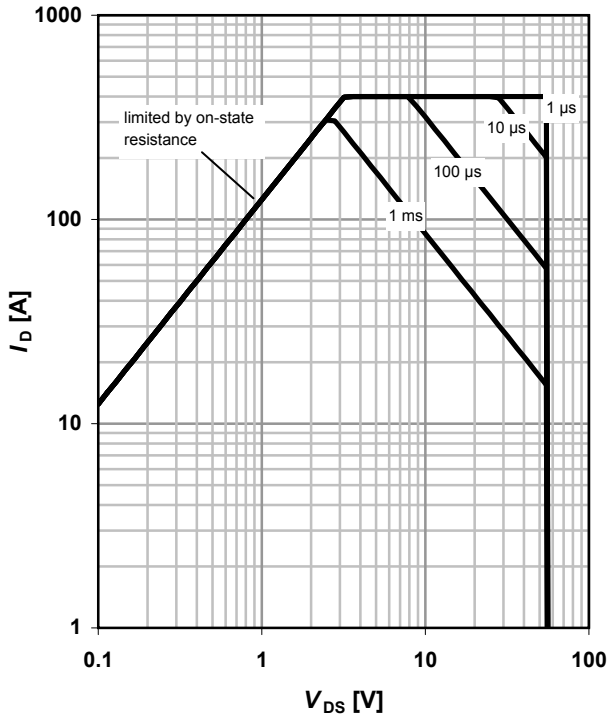
$I_D = f(T_C)$; $V_{GS} \geq 6$ V



3 Safe operating area

$I_D = f(V_{DS})$; $T_C = 25$ °C; $D = 0$

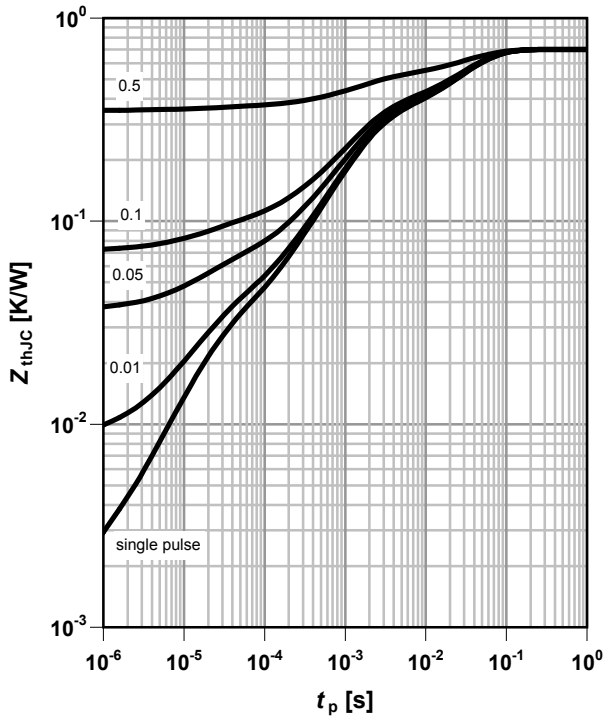
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC} = f(t_p)$

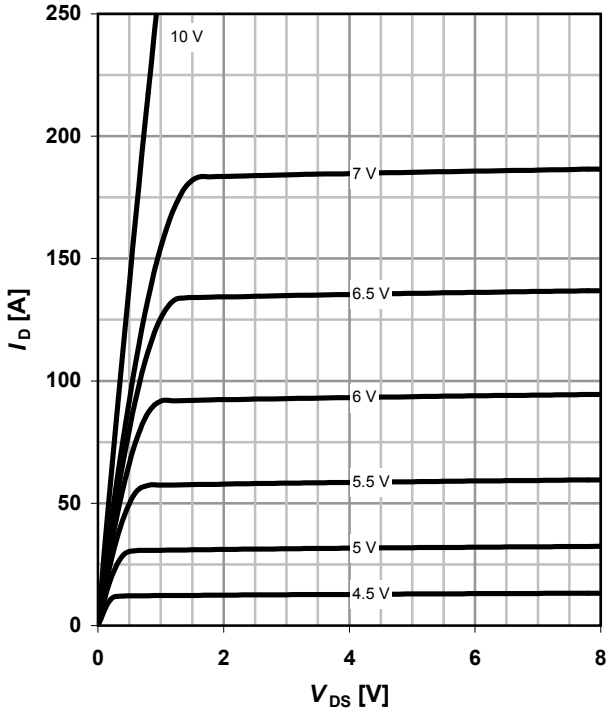
parameter: $D = t_p / T$



5 Typ. output characteristics

$I_D = f(V_{DS})$; $T_j = 25$ °C

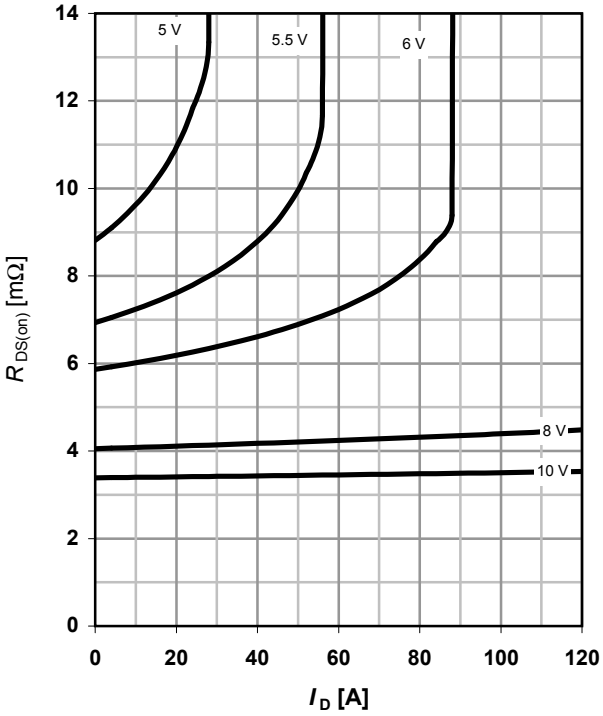
parameter: V_{GS}



6 Typ. drain-source on-state resistance

$R_{DS(on)} = (I_D)$; $T_j = 25$ °C

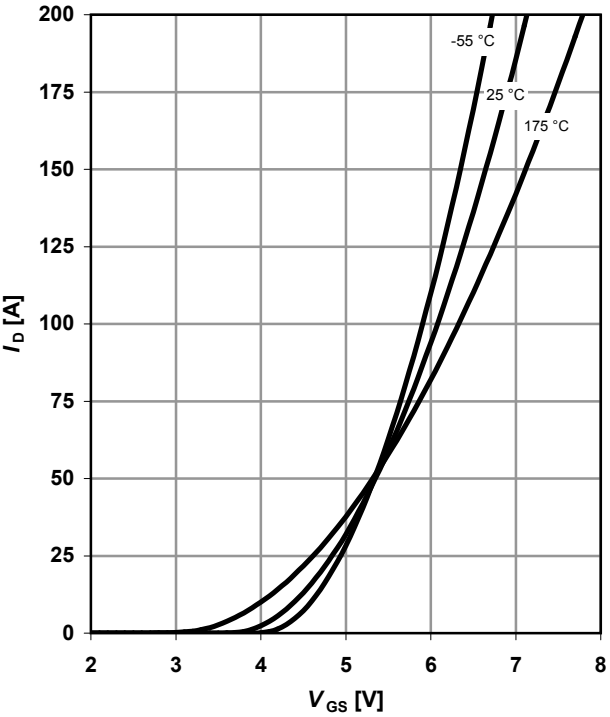
parameter: V_{GS}



7 Typ. transfer characteristics

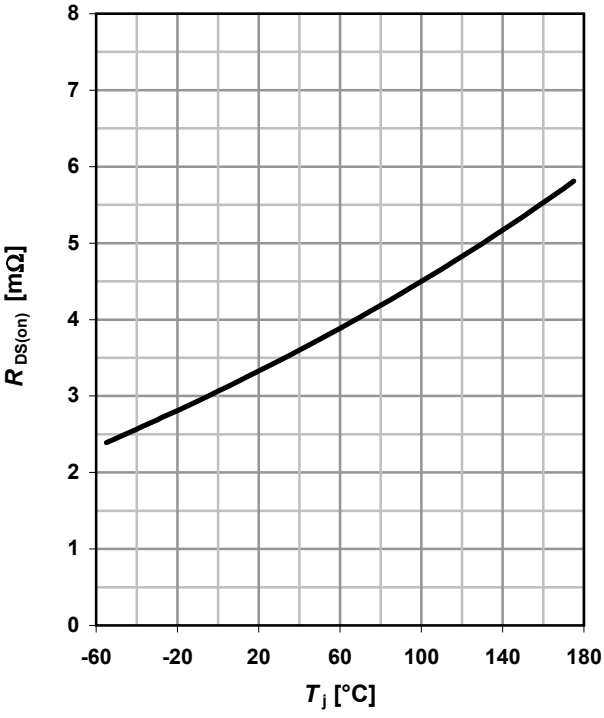
$I_D = f(V_{GS})$; $V_{DS} = 6$V

parameter: T_j



8 Typ. drain-source on-state resistance

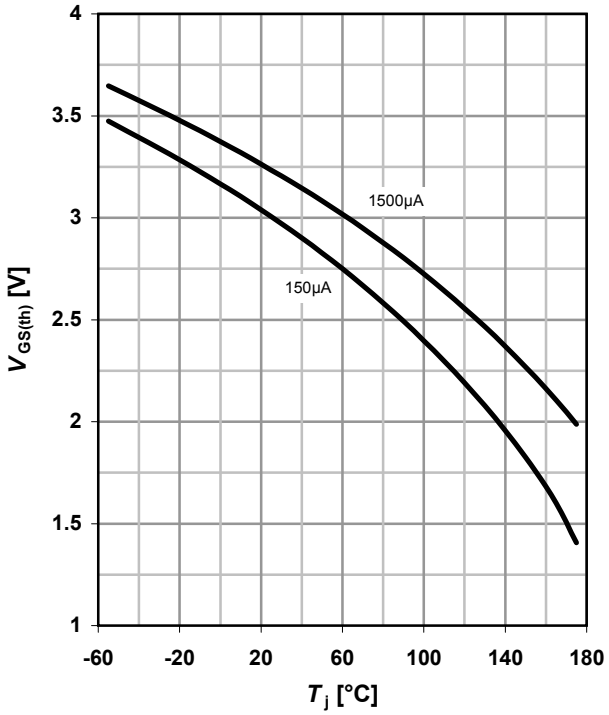
$R_{DS(on)} = f(T_j)$; $I_D = 80$ A; $V_{GS} = 10$ V



9 Typ. gate threshold voltage

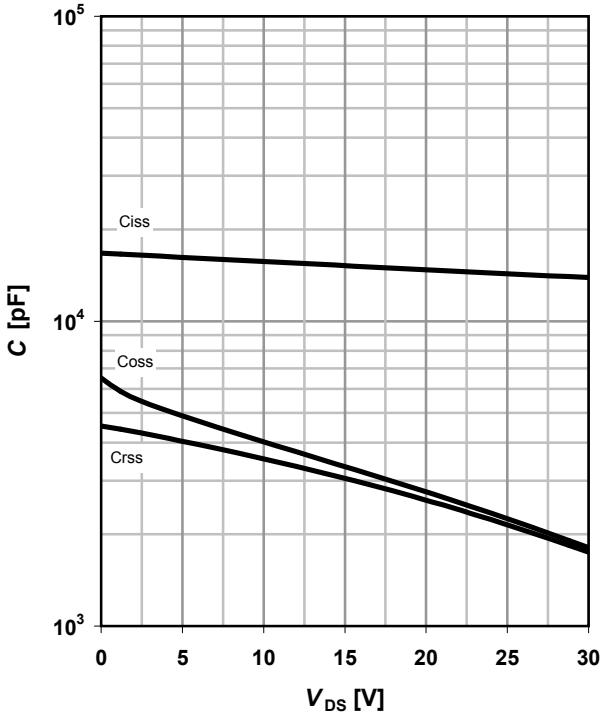
$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$

parameter: I_D



10 Typ. capacitances

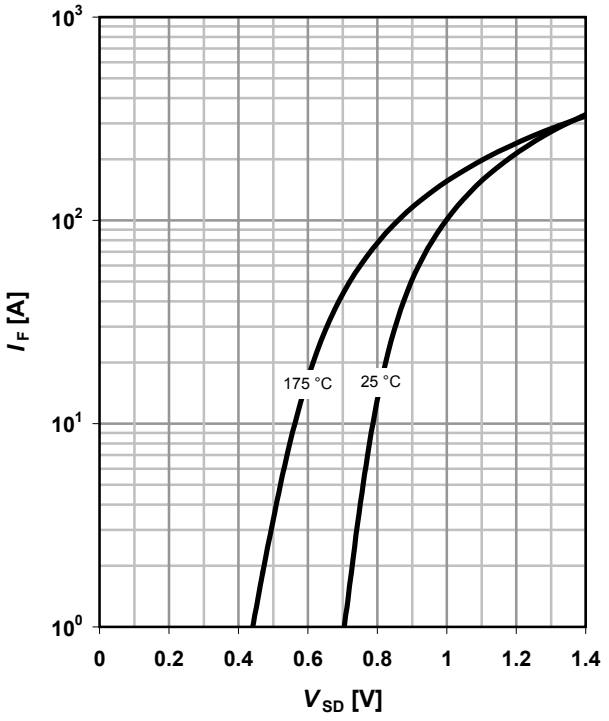
$C = f(V_{DS})$; $V_{GS} = 0$ V; $f = 1$ MHz



11 Typical forward diode characteristicis

IF = f(V_{SD})

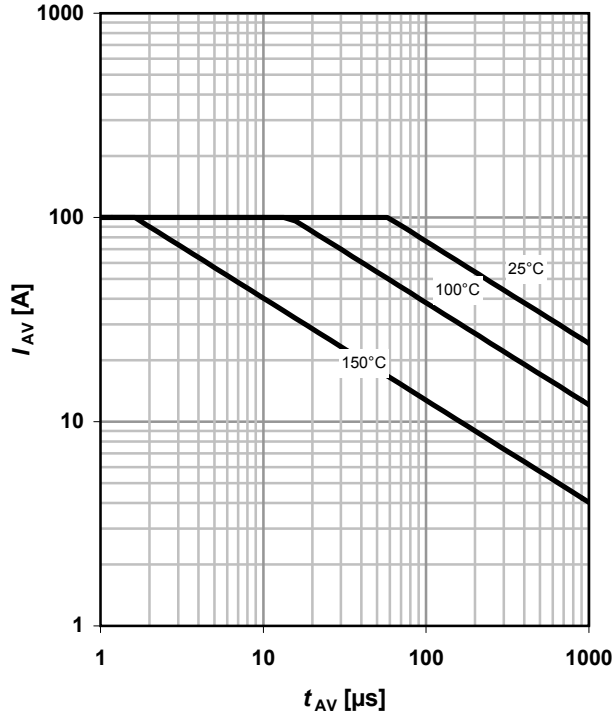
parameter: T_j



12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$

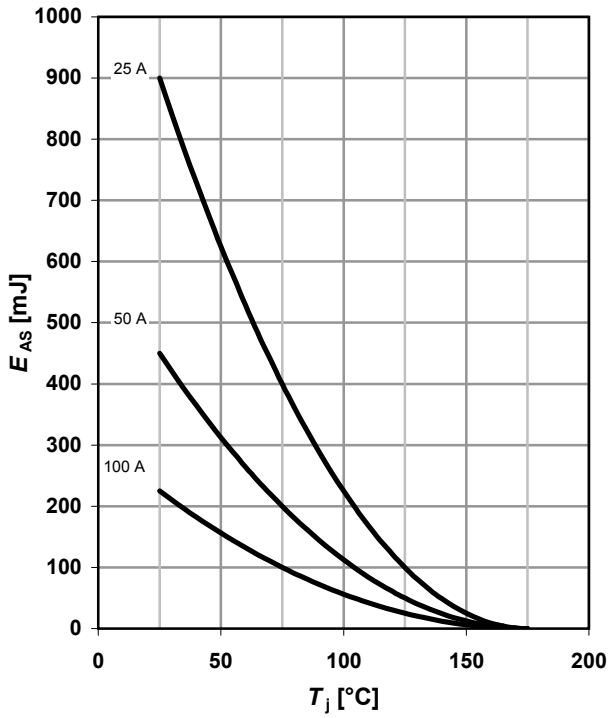
parameter: $T_{j(start)}$



13 Typical avalanche energy

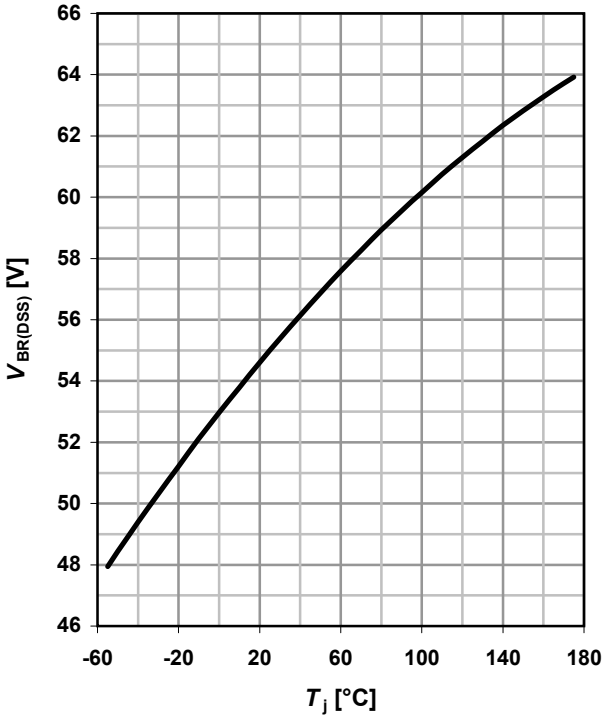
$E_{AS} = f(T_j)$

parameter: I_D



14 Typ. drain-source breakdown voltage

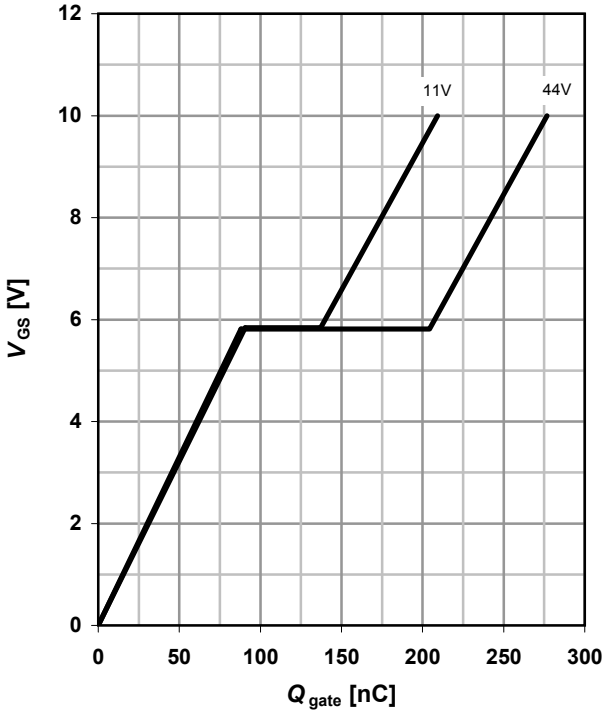
$V_{BR(DSS)} = f(T_j)$; $I_D = 1$ mA



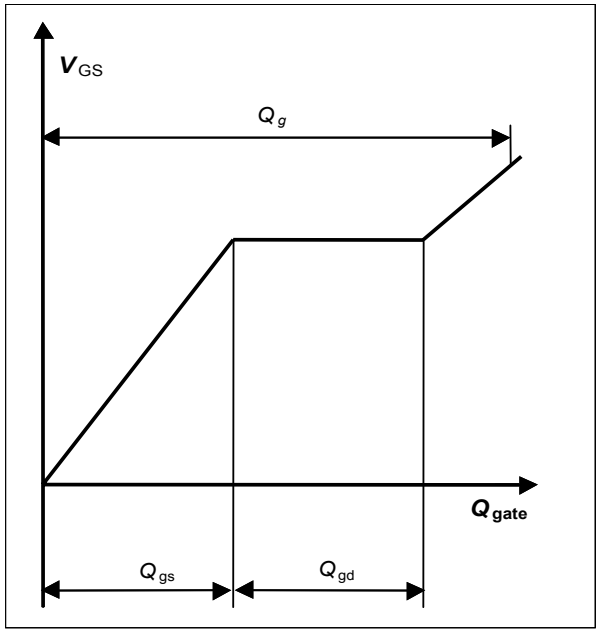
15 Typ. gate charge

$V_{GS} = f(Q_{gate})$; $I_D = 80$ A pulsed

parameter: V_{DD}



16 Gate charge waveforms



Published by
Infineon Technologies AG
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D-81541 München
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